

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
Chao-Chun Tu		05/22/2006
Ming-Chieh Lin		05/22/2006
RECEIVING PARTY DATA		
Name:	MediaTek Inc.	
Street Address:	5F, No. 1-2, Innovation Road 1, Science-Based Industrial Park	
City:	Hsin-Chu Hsien	
State/Country:	TAIWAN	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	11421771	
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ATTORNEY DOCKET NUMBER:	MTKP0359USA	
NAME OF SUBMITTER:	WINSTON HSU	
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REEL: 017709 FRAME: 0675

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Docket No MTKP0359USA

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Chao-Chun Tu Nationality: R.O.C.

Address: 12F, No. 41-3, Shihpin Rd., Hsin-Chu City, Taiwan, R.O.C.

Name: Ming-Chieh Lin Nationality: R.O.C.

Address: No. 10, Alley 12, Lane 34, Hsianjheng 14th St., Jhubei City, Hsin-Chu Hsien, Taiwan, R.O.C.

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: MediaTek Inc.

Address: 5F, No. 1-2, Innovation Road 1, Science-Based Industrial Park, Hsin-Chu Hsien, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"METHOD OF REDUCING CURRENT LEAKAGE IN A METAL INSULATOR METAL SEMICONDUCTOR CAPACITOR AND SEMICONDUCTOR CAPACITOR THEREOF"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this May 22, 2006 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Chao-Chun Tu

Ming-Chieh Lin

Signature of INVENTOR

Chao-Chun Tu

Ming-Chieh Lin